

Title (en)
HOT PLATE AND CONDUCTIVE PASTE

Title (de)
HEIZPLATTEN UND LEITFÄHIGE PASTE

Title (fr)
PLAQUE CHAUFFANTE ET PATE CONDUCTRICE

Publication
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Application
EP 00922932 A 20000501

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• JP 2000126785 A 20000427

Abstract (en)
A hot plate having a conductive pattern layer that does not expand much and has superior adhesion. The hot plate (3) has a conductive pattern layer (10, 10a) arranged on a ceramic nitride substrate (9). The conductive pattern layer (10, 10a) includes bismuth or bismuth oxide, glass frit, and noble metal grains. <IMAGE>

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Citation (search report)
See references of WO 0069220A1

Cited by
WO2009134646A1; WO2082467A1; US7157023B2; US7914709B2; DE102015119763A1; WO2017084980A1; US10785830B2; TWI477474B; TWI567043B

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